

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Hiroyuki Sakamoto et al.

Application No.: 10/528,153

Confirmation No.: 2814

Filed: August 19, 2005

Art Unit: 1795

For: METHOD OF ADHESION OF CONDUCTIVE  
MATERIALS, LAMINATE, AND ADHESIVE  
COMPOSITION

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Examiner: TAI, Xiuyu

**SUPPLEMENTAL RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

This is in a supplemental response to the Office Action dated August 5, 2008.

**No Amendments to the Claims** have been made in this paper.

**Remarks/Arguments** begin on page 2 of this paper.